



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP027N08N5	Issued	17. February 2022
MA#	MA005698662		
Package	PG-TO220-3-1	Weight*	2038.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.993	0.20	0.20	1958	1958
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		400	
	non noble metal	copper	7440-50-8	815.335	40.00	40.05	399895	400415
wire	non noble metal	aluminium	7429-90-5	12.663	0.62	0.62	6211	6211
encapsulation	inorganic material	zinc oxide	1314-13-2	5.902	0.29		2895	
	miscellaneous	miscellaneous	-	23.609	1.16		11580	
	plastics	epoxy resin	-	88.535	4.34		43423	
	inorganic material	silicon dioxide	60676-86-0	472.184	23.16	28.95	231591	289489
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10527	10527
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.073			36	
	noble metal	silver	7440-22-4	0.091			45	
	non noble metal	lead	7439-92-1	3.481	0.17	0.17	1708	1789
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.91	28.95	289114	289490
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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